### Kun Zhang

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#### **Education**

Northeastern University present

PhD in Electrical and Computer Engineering Boston, MA

Carnegie Mellon University 2023/05

Master of Science in Materials Science and Engineering Pittsburgh, PA

Virginia Tech 2020/05

Bachelor of Science in Materials Science and Engineering Blacksburg, VA

### Research Experience

## PLD (Pulsed Laser Deposition) Project: high-performance Ohmic contact structures 2022/05 – 2023/05 Research Assistant

- Investigated the high-performance Ohmic Contact structures on  $\beta\text{-}Ga2O3$  Using n+ type  $\beta\text{-}Ga2O3$  by PLD
- Fabricated CTLM devices and characterized microstructural and electrical properties by using AFM, SEM, and I-V measurements; and optimized the fabrication process to get high-performance contacts
- Concluded that Ti/Au is the most stable metal for ohmic contact with the n+ type  $\beta$ -Ga2O3 layer on account of its continuous/smooth morphology and low contact resistance

#### Ni/Au and Co/Au Schottky contacts on Sn-doped β-Ga2O3 substrates

2021/08 - 2022/05

Research Assistant

- Investigated profoundly the thermal stability of Ni/Au and Co/Au Schottky contacts on Sn-doped ( $\mathbb{Z}$ 01)  $\beta$ -Ga2O3 substrates at 300 °C and 500 °C annealing series
- Characterized the electrical properties and microstructural contacts by SEM, TEM, AFM, and I-V/C-V measurements, and quantified changes in electrical properties of metal-semiconductor contacts as a function of annealing time and temperature
- Learned about how the annealing temperature affects the properties of Ni/Au and Co/Au Schottky contacts

# $\textbf{Double-Side Cooled SiC MOSFET Power Modules with Sintered-Silver Interposers} \ 2020/08-2021/05 \\ \textit{Research Assistant}$

- Designed a double-side cooled SiC power module with sintered silver interposer for a 100 kW/L Traction Inverter
- Simulated the thermal and mechanical performance of power electronic modules on computer, characterizing thermal adhesion properties of epoxy resins for encapsulating, die-attach, and post attach for modules

#### **Undergraduate Thesis: Field Grading Materials**

- Designed and fabricated a polymer-ceramic composite material that is capable of functioning as a field-grading material used in high voltage power modules
- Learned about how the ratio of ceramic fillers to polymer matrix affects the field-grading behaviors including nonlinearity and switching field of the polymer composites

#### Skills

**Programming Skills:** Python, Matlab

**Tech Skills:** Ansys, Mathematica, Autodesk CAD, Hall effect Measurements, SEM, AFM, Micro and Nano Fabrication